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Title: High Performance Thermal Interface Curing Process for Organic Flip Chip Packages

1st Named Inventor: Nagesh Vodrahalli

Application No.: 09/475,104

Docket No.: 42390P6785

Sheet: 1 of 1

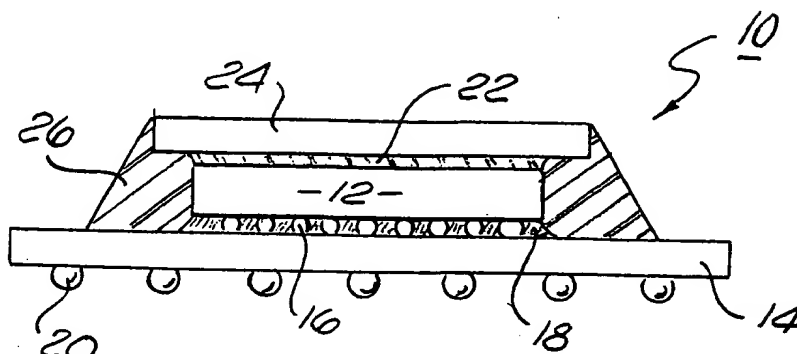


FIG. 1

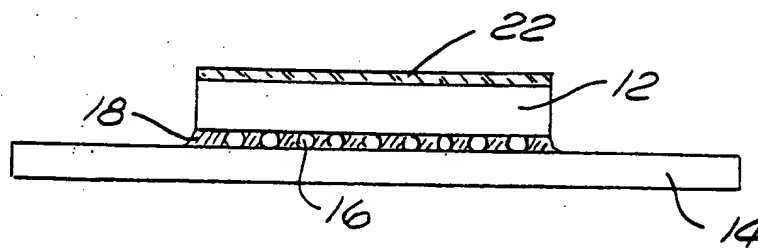


FIG. 2a

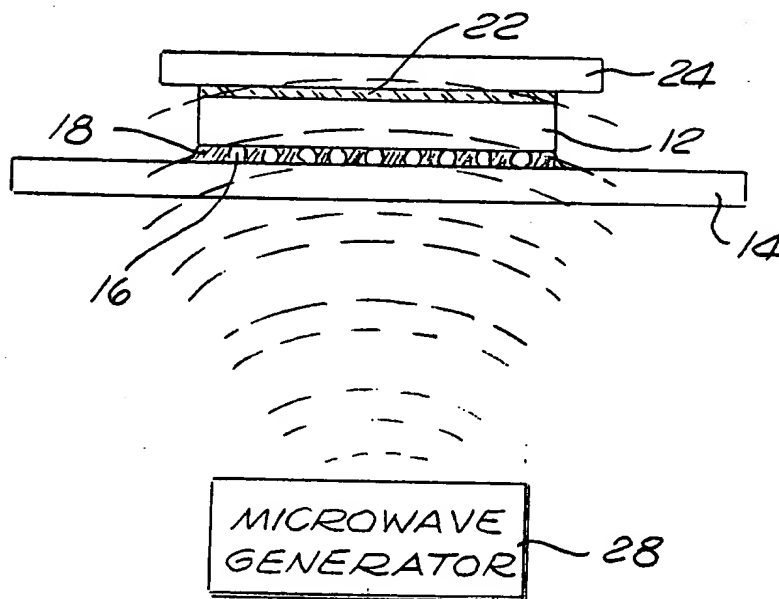


FIG. 2b